



## Supporting Information

for

### **Sputtering onto liquids: a critical review**

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### **Comparison the sizes of the metal NPs prepared by magnetron sputtering onto similar host liquids**

Depositions were done in the sputter coaters with 2-inch metal targets, at temperatures of 20–25 °C. Parameters:  $p$  – pressure (Pa),  $WD$  – working distance (mm),  $V$  – voltage (V),  $I$  – current (mA),  $t_s$  – duration of deposition (min), NP size – diameter of NPs determined by TEM (nm).

**Table S1:** Sputtering onto ionic liquid TMPA-TFSI.

Target	Amount of liquid substrate	$p$ , Pa	$WD$ , mm	$V$ , V	$I$ , mA	$t_s$ , min	NP size (nm)	Ref.
Pt	0.4 cm <sup>3</sup> of IL on a glass plate (2.5 x 2.5 cm)	7	45		40	5	2.24±0.36	[1]
Pt	0.2 cm <sup>3</sup> of IL on a glass plate (2.5 x 2.5 cm)	7	45		40	5 → 30	2.3-2.4	[2]
Pt AuPt Au	IL was spread on a glass plate 10 cm <sup>2</sup>	10	20	500	40	5	1.0 ± 0.3 1.5 ± 0.4 2.9 ± 0.7	[3]
Au	0.8 cm <sup>3</sup> of IL on a glass plate 4 cm <sup>2</sup>	20	35		10	5	2.2±0.4	[4]
Au	0.6 cm <sup>3</sup> of IL on a glass plate 10 cm <sup>2</sup>	20	35		40	5	2.3±0.3	[5]

**Table S2:** Sputtering onto ionic liquid BMIM-PF<sub>6</sub>.

Target	Amount of liquid substrate	$p$ , Pa	$WD$ , mm	$P$ , W	$V$ , V	$I$ , mA	$t_s$ , min	NP size (nm)	Ref.
Au	0.6 cm <sup>3</sup> of IL on a glass plate 10 cm <sup>2</sup>	20	35			40	5	2.6 ± 0.3	[6]
Au	0.6 cm <sup>3</sup> of IL on a glass (26 x 38x 1mm3)	20	30			40	5	2.3 ± 0.4	[7]
Au	0.60 cm <sup>3</sup> of IL on a glass slide (5.7 cm <sup>2</sup> )	20	35			40	5	2.5	[8]
Au	0.60 cm <sup>3</sup> of IL on a glass slide (10 cm <sup>2</sup> )	20	35			40	5	2.6±0.6	[9]
Au	2.0 cm <sup>3</sup> of IL on a stainless plate 15.9 cm <sup>2</sup>	16-19	25		1000	20	50	1.0–1.5	[10]
Au	1.0 cm <sup>3</sup> of IL on a Teflon plate 6.1 cm <sup>2</sup>	20	35			40	5	2.6±0.3	[11]
Ag	1.0 cm <sup>3</sup> of IL on a Teflon plate 6.1 cm <sup>2</sup>	20	35			40	5	6±1.5	[11]
Ag	multiple cavity holder (40 $\mu$ L per cavity)	0.5		30			15	6±3	[12]
Ag	0.6 cm <sup>3</sup> of IL on a glass plate 10 cm <sup>2</sup>	5	85			10	5	5.7±1.8	[13]
		5	85			40	5	11	
Pd	0.2 cm <sup>3</sup> of IL on a glass plate (2.5 x 2.5 cm)	8	45			40	5	3.0	[14]

**Table S3:** Sputtering onto ionic liquid BMIM-TFSI.

Target	Amount of liquid substrate	$p$ , Pa	$WD$ , mm	$P$ , W	$V$ , V	$I$ , mA	$t_s$ , min	NP size (nm)	Ref.
Pd	0.2 cm <sup>3</sup> of IL on a glass plate (2.5 x 2.5 cm)	8	45			40	5	2.2	[14]
Au	0.6 cm <sup>3</sup> of IL on a glass (26 x 38x 1 mm3)	20	30			40	5	2.0 ± 0.4	[7]
Au	3.5 cm <sup>3</sup> of IL was poured in a PTFE container ( $\phi$ =4 cm)	10	40			50	1	5-6	[15]
Ag	multiple cavity holder (40 $\mu$ L per cavity)	0.5		30			15	8±4	[12]
Ag	4 cm <sup>3</sup> of IL into a cylindrical ceramic crucible ( $\phi$ =4.5 cm)	1.3	150	20			20	5-20	[16]

**Table S4:** Sputtering onto pure PEG-600.

Target	Amount of liquid substrate	$p$ , Pa	$WD$ , mm	$V$ , V	$I$ , mA	$t_s$ , min	NP size (nm)	Ref.
Pt	2 ml on a Petri plate	8	50		30		3.9	[17]
Au	2 ml on a Petri plate	8	50		30		6.3	[17]
Au	2 ml on a Petri plate ( $\phi$ = 4 cm)	10	50	420-430	30	5 and 15	5.6±1.9	[18]
Au	2 ml on a Petri plate ( $\phi$ = 4 cm)	10	50	420-430	30	5	5.6±1.8	[19]
Ag		2	50		30	20	7.4±3.6	[20]

**Table S5:** Sputtering onto pure glycerol.

Target	Amount of liquid substrate	$p$ , Pa	$WD$ , mm	$V$ , V	$I$ , mA	$t_s$ , min	NP size (nm)	Ref.
Pt	5 ml on a Petri plate ( $\phi$ = 4cm)	4-6	50	420	40	5	1.7±0.3	[21]
Pd	5 ml on a Petri plate ( $\phi$ = 4cm)	4-6	50	420	40	5	2.4±0.4	[21]
Au	2 ml on a Petri plate ( $\phi$ = 4cm)	7	50		30	5	3.5 ±1.5	[22]
Ag	2 ml on a Petri plate ( $\phi$ = 4cm)	7	50		30	5	3.5 ±2.4	[22]

## References

- (1) Tsuda, T.; Kurihara, T.; Hoshino, Y.; Kiyama, T.; Okazaki, K.; Torimoto, T.; Kuwabata, S. *Electrochemistry* **2009**, *77*, 693–695. doi:10.5796/electrochemistry.77.693
- (2) Tsuda, T.; Yoshii, K.; Torimoto, T.; Kuwabata, S. *J. Power Sources* **2010**, *195*, 5980–5985. doi:10.1016/j.jpowsour.2009.11.027
- (3) Suzuki, S.; Suzuki, T.; Tomita, Y.; Hirano, M.; Okazaki, K.; Kuwabata, S.; Torimoto, T. *CrystEngComm* **2012**, *14*, 4922. doi:10.1039/c2ce25235j
- (4) Sugioka, D.; Kameyama, T.; Kuwabata, S.; Torimoto, T. *Phys. Chem. Chem. Phys.* **2015**, *17*, 13150–13159. doi:10.1039/c5cp01602a
- (5) Okazaki, K. I.; Kiyama, T.; Suzuki, T.; Kuwabata, S.; Torimoto, T. *Chem. Lett.* **2009**, *38*, 330–331. doi:10.1246/cl.2009.330
- (6) Khatri, O. P.; Adachi, K.; Murase, K.; Okazaki, K. I.; Torimoto, T.; Tanaka, N.; Kuwabata, S.; Sugimura, H. *Langmuir* **2008**, *24*, 7785–7792. doi:10.1021/la800678m
- (7) Suzuki, S.; Ohta, Y.; Kurimoto, T.; Kuwabata, S.; Torimoto, T. *Phys. Chem. Chem. Phys.* **2011**, *13*, 13585–13593. doi:10.1039/c1cp20814d
- (8) Okazaki, K. I.; Sakuma, J.; Yasui, J. I.; Kuwabata, S.; Hirahara, K.; Tanaka, N.; Torimoto, T. *Chem. Lett.* **2011**, *40*, 84–86. doi:10.1246/cl.2011.84
- (9) Kameyama, T.; Ohno, Y.; Kurimoto, T.; Okazaki, K.; Uematsu, T.; Kuwabata, S.; Torimoto, T. *Phys. Chem. Chem. Phys.* **2010**, *12*, 1804–1811. doi:10.1039/B914230D
- (10) Iimori, T.; Hatakeyama, Y.; Nishikawa, K.; Kato, M.; Ohta, N. *Chem. Phys. Lett.* **2013**, *586*, 100–103. doi:10.1016/j.cplett.2013.09.010
- (11) Okazaki, K.; Kiyama, T.; Hirahara, K.; Tanaka, N.; Kuwabata, S.; Torimoto, T. *Chem. Commun.* **2008**, No. 6, 691–693. doi:10.1039/B714761A
- (12) Meyer, H.; Meischein, M.; Ludwig, A. *ACS Comb. Sci.* **2018**, *20*, 243–250. doi:10.1021/acscombsci.8b00017
- (13) SUZUKI, T.; OKAZAKI, K.; KIYAMA, T.; KUWABATA, S.; TORIMOTO, T. *Electrochemistry* **2009**, *77*, 636–638. doi:10.5796/electrochemistry.77.636
- (14) Oda, Y.; Hirano, K.; Yoshii, K.; Kuwabata, S.; Torimoto, T.; Miura, M. *Chem. Lett.* **2010**, *39*, 1069–1071. doi:10.1246/cl.2010.1069
- (15) Vanecht, E.; Binnemans, K.; Patskovsky, S.; Meunier, M.; Seo, J. W.; Stappers, L.; Fransaer, J. *Phys. Chem. Chem. Phys.* **2012**, *14*, 5662. doi:10.1039/c2cp23677j
- (16) Carette, X.; Debièvre, B.; Cornil, D.; Cornil, J.; Leclère, P.; Maes, B.; Gautier, N.; Gautron, E.; El Mel, A. A.; Raquez, J. M.; Konstantinidis, S. *J. Phys. Chem. C* **2018**, *122*, 26605–26612. doi:10.1021/acs.jpcc.8b06987
- (17) Pišlová, M.; Kalbáčová, M. H.; Vrabcová, L.; Slepíčka, P.; Kolská, Z.; Švorčík, V. *Dig. J. Nanomater. Biostructures* **2018**, *13*, 1035–1044
- (18) Rezníčková, A.; Slavikova, N.; Kolska, Z.; Kolarova, K.; Belinova, T.; Hubalek Kalbacova, M.; Cieslar, M.; Svorcik, V. *Colloids Surfaces A Physicochem. Eng. Asp.* **2019**, *560*, 26–34. doi:10.1016/j.colsurfa.2018.09.083
- (19) Rezníčková, A.; Slepicka, P.; Slavikova, N.; Staszek, M.; Svorcik, V. *Colloids Surfaces A Physicochem. Eng. Asp.* **2017**, *523*, 91–97. doi:10.1016/j.colsurfa.2017.04.005
- (20) Ishida, Y.; Nakabayashi, R.; Matsubara, M.; Yonezawa, T. *New J. Chem.* **2015**, *39*, 4227–4230. doi:10.1039/c5nj00294j
- (21) Staszek, M.; Siegel, J.; Kolářová, K.; Rimpelová, S.; Švorčík, V. *Micro Nano Lett.* **2014**, *9*, 778–781. doi:10.1049/mnl.2014.0345
- (22) Siegel, J.; Kvítek, O.; Ulbrich, P.; Kolská, Z.; Slepíčka, P.; Švorčík, V. *Mater. Lett.* **2012**, *89*, 47–50. doi:10.1016/j.matlet.2012.08.048